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TI Cladding materials for **sputtering targets**  
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PA Tanaka Noble Metal Industrial Co., Ltd., Japan  
SO Jpn. Kokai Tokkyo Koho, 3 pp.  
CODEN: JKXXAF

DT Patent  
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 01096374	A2	19890414	JP 1987-251174	19871005
PRAI	JP 1987-251174		19871005		
AB	The material is made of <b>Cu</b> >99.7%, and Zn, In, Mn, Sb, Be, Ca, Cr, Te, Y, Nb, Mo, Ta, and/or <b>Sn</b> 100-3000 ppm for separation of the backing plate in exchange of the <b>target</b> and efficient cooling.				